DECLARATION FOR NON-PROVISIONAL PATENT APPLICATION'

	As a below named	inventor.	I hereby	declare	that:
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My residence, post office address and citizenship are as stated below at 201 et seq. beneath my name.

I believe I am the original, first and are listed at 201 et seq. below, of the							f plural names
A COMPLEX MEMBRANE FOR I	ELECTROCHEMICAL DEV	ICE, M	ANUFACTURIN	IG METHOD AND	ELECTR	OCHEM	MICAL DEVICE
and for which a patent application:							
is attached hereto and include	s amendment(s) filed on JAN	UARY	17, 2005 (if applicabl	e)			
was filed in the United States with amendment(s) filed on @	= =	claration no	t accompanying application	n)			
was filed as PCT internationa January 17, 2005(if applicable)	Application No. PCT/KR20	04/0007	750 on	and was amende	ed under PO	CT Artic	cle 34 on
I hereby authorize and request my a date and application number of said	ttorneys at Jones Day to inser application when known.	t herein	parentheses (App	olication No.	filed) the filing
I hereby state that I have reviewed a amendment referred to above	and understand the contents of	f the abo	ove identified app	lication, including t	he claims,	as amen	ided by any
I acknowledge the duty to disclose i Regulations, §1.56.	information known to me to b	e mater	ial to patentability	as defined in Title	37, Code o	of Federa	al
I hereby claim foreign priority bene certificate listed below and have als of the application on which priority	o identified below any foreign						
EARLIEST FOREIGN	APPLICATION(S), IF ANY	, FILEC	PRIOR TO THE	FILING DATE O	F THE API	PLICAT	TION
APPLICATION NUMBER	COUNTRY			F FILING onth, year)	PRI	ORITY	CLAIMED
10-2003-0039239	Korea		June 17, 2003		YES 🖾		NO □
10-2003-0093184	Korea		December 18, 2	003	YES 🛛		NO 🗆
I hereby claim the benefit under Tit	le 35, United States Code, §1	19(e) of	any United States	s provisional applic	ation(s) lis	ted belo	w.
PROVISIONAL APPI	LICATION NUMBER			FILING	DATE		
_							
I hereby claim the benefit under Tit matter of each of the claims of this paragraph of Title 35, United States as defined in Title 37, Code of Fede national or PCT international filing	application is not disclosed in Code §112, I acknowledge the eral Regulations, §1.56 which	the priche duty	or United States a to disclose inform	pplication in the ma	nner provi	ded by t	the first to patentability
NON-PROVISIONAL	FILING DATE			STATU	s		
APPLICATION SERIAL NO.		P	ATENTED	PENDING	1	AE	BANDONED
			· · ·				

for use only when the application is assigned to a company, partnership or other organization.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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